

ABSTRACT

The present disclosure discloses a conductive slip ring and semiconductor process equipment. The disclosed conductive slip ring is applied to a process chamber of the semiconductor process equipment. The conductive slip ring includes a housing, a stationary electrical connection part, and a rotary electrical connection part. The housing includes a housing cavity and a first mounting hole communicating with the housing cavity. The housing is configured to be sealingly connected to the process chamber, so that the housing cavity is in sealed connection with a chamber space of the process chamber. The stationary electrical connection part is in sealing engagement with the first mounting hole, and a first end of the stationary electrical connection part extends into the housing cavity and is rotatably electrically connected to the rotary electrical connection part, a second end of the stationary electrical connection part is located outside the housing and configured to be electrically connected to a power supply. The rotary electrical connection part is rotatably disposed within the housing and configured to be electrically connected to an electrical device within the process chamber. The above solution can solve the problem of poor sealing performance in related technologies where the process chamber uses magnetohydrodynamic structures to achieve sealing between the process space and the external environment of the process chamber.